INTEGRATED CIRCUITS

DATA SHEET



74ABT32Quad 2-input OR gate

Product specification

IC23 Data Handbook

1995 Sep 22





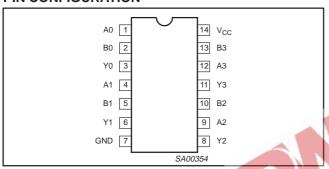
Quad 2-input OR gate

74ABT32

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay An, Bn to Yn	C _L = 50pF; V _{CC} = 5V	2.3 1.9	ns
toslh toshl	Output to Output skew	0.4	ns	
C _{IN}	C_{IN} Input capacitance $V_I = 0V \text{ or } V_{CC}$		3	pF
Icc	Total supply current	Outputs disabled; V _{CC} = 5.5V	50	μΑ

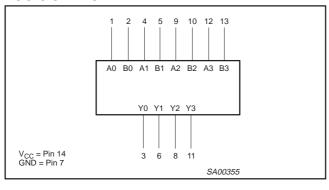
PIN CONFIGURATION



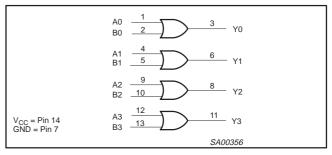
PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 2, 4, 5, 9, 10, 12, 13	An, Bn	Data inputs
3, 6, 8, 11	Yn	Data outputs
7	GND	Ground (0V)
14	V _{CC}	Positive supply voltage

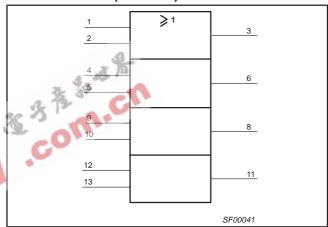
LOGIC SYMBOL



LOGIC DIAGRAM



LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

INF	PUTS	OUTPUT
An	Bn	Yn
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н

NOTES:

H = High voltage level L = Low voltage level

ORDERING INFORMATION

<u> </u>				
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
14-Pin Plastic DIP	-40°C to +85°C	74ABT32 N	74ABT32 N	SOT27-1
14-Pin plastic SO	-40°C to +85°C	74ABT32 D	74ABT32 D	SOT108-1
14-Pin Plastic SSOP Type II	-40°C to +85°C	74ABT32 DB	74ABT32 DB	SOT337-1
14-Pin Plastic TSSOP Type I	-40°C to +85°C	74ABT32 PW	74ABT32PW DH	SOT402-1

Quad 2-input OR gate

74ABT32

ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V _I < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
I _{OK}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V
I _{OUT}	DC output current	output in Low state	40	mA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
 device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
 absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
- 3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		A 30	LIM	ITS	UNIT
31 MIDOL	TANAMETEN		40 %	MIN	MAX	ONIT
V _{CC}	DC supply voltage	4	135	4.5	5.5	V
V _I	Input voltage		Co	0	V _{CC}	V
V _{IH}	High-level input voltage	1		2.0		V
V _{IL}	Low-level input voltage	\			0.8	V
I _{OH}	High-level output current				- 15	mA
I _{OL}	Low-level output current				20	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V		
T _{amb}	Operating free-air temperature range			-40	+85	°C

DC ELECTRICAL CHARACTERISTICS

				LIMITS							
SYMBOL	PARAMETER	TEST CONDITIONS	Tai	_{mb} = +25	5°C	T _{amb} =	-40°C 85°C	UNIT			
			MIN	TYP	MAX	MIN	MAX	1			
V _{IK}	Input clamp voltage	$V_{CC} = 4.5V; I_{IK} = -18mA$		-0.9	-1.2		-1.2	V			
V _{OH}	High-level output voltage	$V_{CC} = 4.5V$; $I_{OH} = -15mA$; $V_I = V_{IL}$ or V_{IH}	2.5	2.9		2.5		V			
V _{OL}	Low-level output voltage	$V_{CC} = 4.5V$; $I_{OL} = 20mA$; $V_I = V_{IL}$ or V_{IH}		0.35	0.5		0.5	V			
lį	Input leakage current	$V_{CC} = 5.5V$; $V_I = GND \text{ or } 5.5V$		±0.01	±1.0		±1.0	μА			
I _{OFF}	Power-off leakage current	$V_{CC} = 0.0V$; V_O or $V_I \le 4.5V$		±5.0	±100		±100	μΑ			
I _{CEX}	Output High leakage current	$V_{CC} = 5.5V$; $V_{O} = 5.5V$; $V_{I} = GND$ or V_{CC}		5.0	50		50	μА			
ΙO	Output current ¹	$V_{CC} = 5.5V; V_{O} = 2.5V$	-50	-75	-180	-50	-180	mA			
I _{CC}	Quiescent supply current	$V_{CC} = 5.5V$; $V_I = GND \text{ or } V_{CC}$		2	50		50	μΑ			
Δl _{CC}	Additional supply current per input pin ²	V_{CC} = 5.5V; One data input at 3.4V, other inputs at V_{CC} or GND		0.25	500		500	μА			

NOTES:

- 1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- 2. This is the increase in supply current for each input at 3.4V.
- 3. For valid test results, data must not be loaded into the flip-flop or latch after applying the power.

Quad 2-input OR gate

74ABT32

AC CHARACTERISTICS

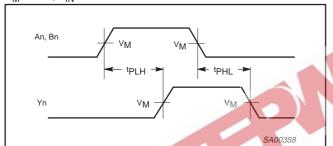
GND = 0V; t_R = t_F = 2.5ns; C_L = 50pF, R_L = 500 Ω

SYMBOL		WAVEFORM						
	PARAMETER		T _a	_{imb} = +25° CC = +5.0°	C V	T _{amb} = -40° V _{CC} = +5.	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay An, Bn to Yn	1	1.0 1.0	2.3 1.9	3.4 2.9	1.0 1.0	3.8 3.2	ns
t _{OSHL} t _{OSLH} 1	Output to Output skew An or Bn to \(\overline{Y}\)n			0.4	0.5		0.5	ns

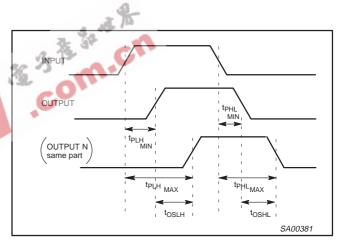
NOTE:

AC WAVEFORMS

 $V_{M} = 1.5V, V_{IN} = GND \text{ to } 3.0V$

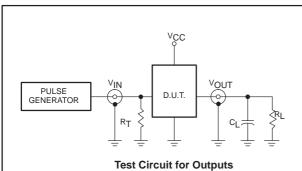


Waveform 1. Propagation delay for inverting outputs



Waveform 2. Common edge skew

TEST CIRCUIT AND WAVEFORMS



AMP (V) 90% NEGATIVE ٧M **PULSE** 10% 10% tTHL (tF) tTLH (tR) tTLH (tR) tTHL (tF) AMP (V) 90% 90% POSITIVE **PULSE** 10% tw $V_{M} = 1.5V$

Input Pulse Definition

FAMILY	IN	INPUT PULSE REQUIREMENTS												
PAWIL	Amplitude	Rep. Rate	t _W	t _R	t _F									
74ABT	3.0V	1MHz	500ns	2.5ns	2.5ns									

SH00067

DEFINITIONS

R_L = Load resistor; see AC CHARACTERISTICS for value.

 $C_L = Load$ capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.

R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

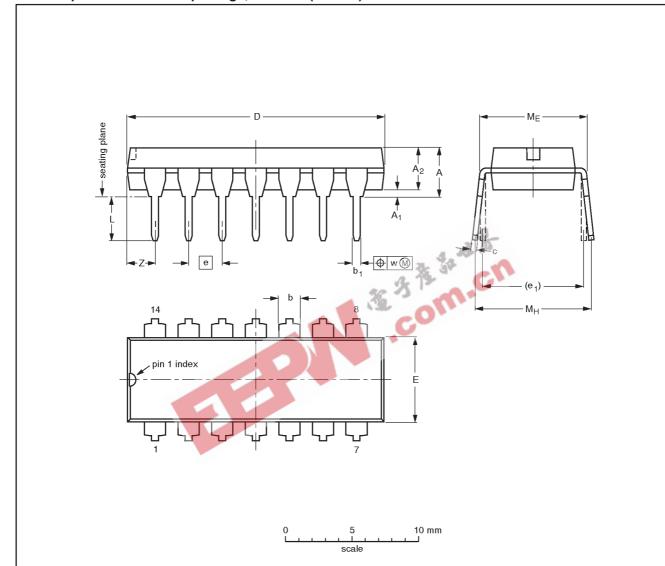
Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

Quad 2-input OR gate

74ABT32

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

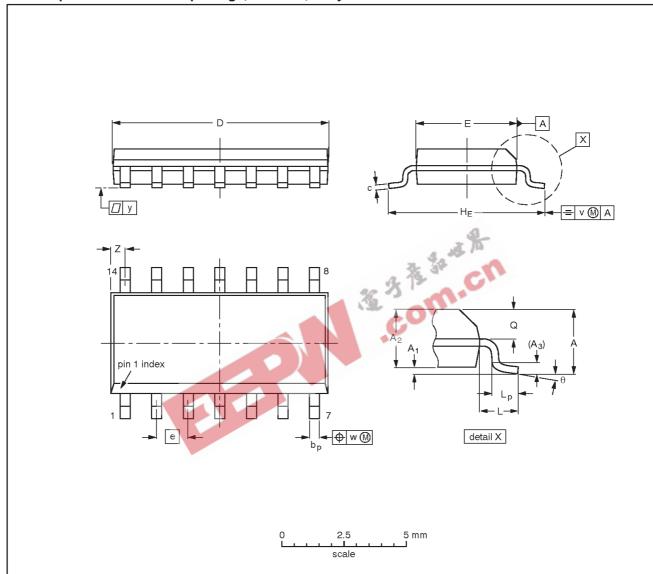
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC JEDEC EIAJ			PROJECTION	ISSUE DATE	
SOT27-1	050G04	MO-001AA				92-11-17 95-03-11

Quad 2-input OR gate

74ABT32

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	А3	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

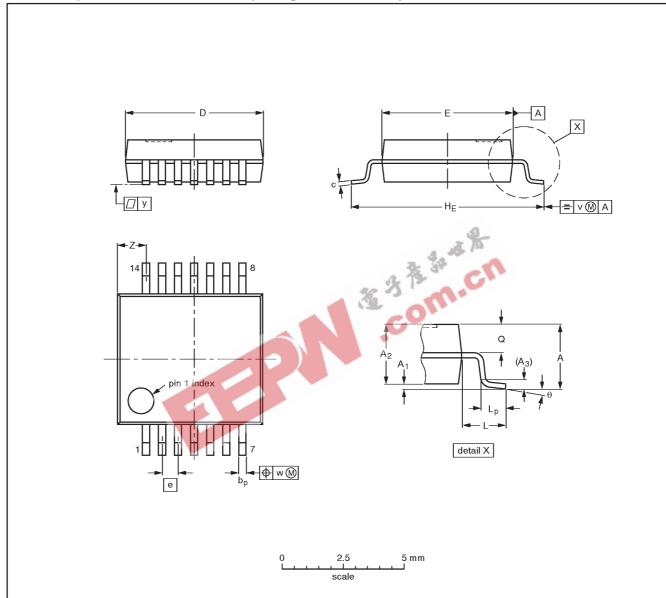
OUTLINE		EUROPEAN	ISSUE DATE				
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT108-1	076E06S	MS-012AB				-95-01-23 97-05-22	

Quad 2-input OR gate

74ABT32

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



DIMENSIONS (mm are the original dimensions)

						-,												
UNIT	A max.	Α ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

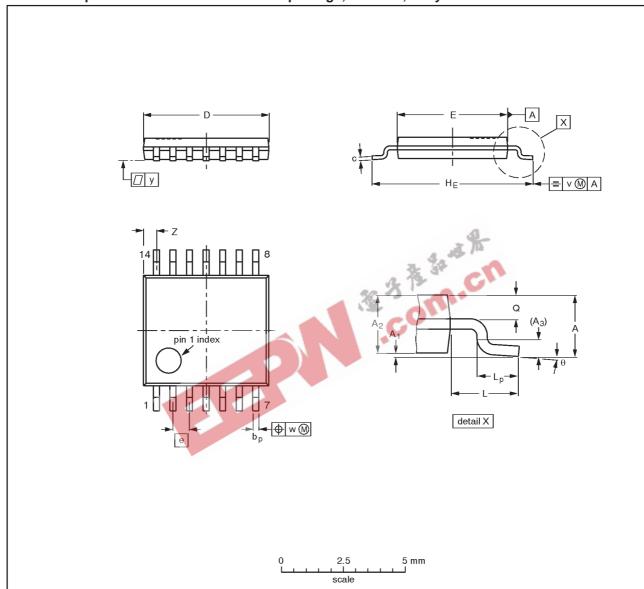
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUEDATE
SOT337-1		MO-150AB				-95-02-04 96-01-18

Quad 2-input OR gate

74ABT32

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	А3	рb	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	٧	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		EUROPEAN	ISSUE DATE				
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1550E DATE	
SOT402-1		MO-153				94-07-12 95-04-04	

Quad 2-input OR gate

74ABT32

NOTES



Quad 2-input OR gate

74ABT32



DEFINITIONS							
Data Sheet Identification	Product Status	Definition					
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.					
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.					
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.					

Philips Semiconductors and Philips Electronics North America Corporation reserve the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified. Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

LIFE SUPPORT APPLICATIONS

Philips Semiconductors and Philips Electronics North America Corporation Products are not designed for use in life support appliances, devices, or systems where malfunction of a Philips Semiconductors and Philips Electronics North America Corporation Product can reasonably be expected to result in a personal injury. Philips Semiconductors and Philips Electronics North America Corporation customers using or selling Philips Semiconductors and Philips Electronics North America Corporation Products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors and Philips Electronics North America Corporation for any damages resulting from such improper use or sale.

Philips Semiconductors 811 East Arques Avenue P.O. Box 3409 Sunnyvale, California 94088–3409 Telephone 800-234-7381 Philips Semiconductors and Philips Electronics North America Corporation register eligible circuits under the Semiconductor Chip Protection Act.

© Copyright Philips Electronics North America Corporation 1995

All rights reserved. Printed in U.S.A.

(print code) Date of release: July 1994

Document order number: 9397-750-04848